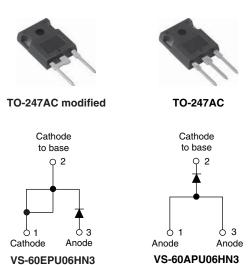


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Vishay Semiconductors

Ultrafast Soft Recovery Diode, 60 A FRED Pt®



PRODUCT SUMMARY						
Package	TO-247AC modified (2 pins), TO-247AC					
I _{F(AV)}	60 A					
V_{R}	600 V					
V _F at I _F	1.11 V					
t _{rr} typ.	See Recovery table					
T _J max.	175 °C					
Diode variation	Single die					

FEATURES

- · Ultrafast recovery time
- Low forward voltage drop
- 175 °C operating junction temperature
- AEC-Q101 qualified, meets JESD 201 class 1A whisker test
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





ROHS COMPLIANT HALOGEN FREE

BENEFITS

- Reduced RFI and EMI
- Higher frequency operation
- · Reduced snubbing
- · Reduced parts count

DESCRIPTION / APPLICATIONS

These diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems.

The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for HF welding, power converters and other applications where switching losses are not significant portion of the total losses.

ABSOLUTE MAXIMUM RATINGS						
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS		
Cathode to anode voltage	V _R		600	V		
Continuous forward current	I _{F(AV)}	T _C = 116 °C	60			
Single pulse forward current	I _{FSM}	T _C = 25 °C	600	Α		
Maximum repetitive forward current	I _{FRM}	Square wave, 20 kHz	120			
Operating junction and storage temperatures	T _J , T _{Stg}		-55 to +175	°C		

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	TEST CONDITIONS MIN. TYP. MAX				
Breakdown voltage, blocking voltage	V _{BR} , V _R	Ι _R = 100 μΑ	600	-	1		
Forward voltage	V _F	I _F = 60 A	-	1.35	1.68	V	
		I _F = 60 A, T _J = 125 °C	-	1.20	1.42		
		I _F = 60 A, T _J = 175 °C	-	1.11	1.30		
Reverse leakage current	I _R	$V_R = V_R$ rated	-	i	50		
		$T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$	-	-	500	μΑ	
Junction capacitance	C _T	V _R = 600 V	-	39	-	pF	



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	MIN.	TYP.	MAX.	UNITS		
		$I_F = 1 A, dI_F/dt = 20$	$I_F = 1 \text{ A}, dI_F/dt = 200 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		34	45		
Reverse recovery time	t _{rr}	T _J = 25 °C		-	81	-	ns	
		T _J = 125 °C	$I_F = 60 \text{ A}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_R = 200 \text{ V}$	-	164	-		
Peak recovery current	I _{RRM}	T _J = 25 °C		-	7.4	-	А	
		T _J = 125 °C		-	17.0	-		
Develope	0	T _J = 25 °C		-	300	-	200	
Reverse recovery charge	Q _{rr}	T _J = 125 °C		-	1394	-	nC	

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Thermal resistance, junction to case	R _{thJC}		-	-	0.63	K/W	
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.2	-	- K/VV	
Weight			-	5.5	-	g	
vveignt			-	0.2	-	OZ.	
Mounting torque			1.2 (10)	-	2.4 (20)	N ⋅ m (lbf ⋅ in)	
Mauldan daria		Case style TO-247AC modified		60EPU06H			
Marking device		Case style TO-247AC		60AF	PU06H		

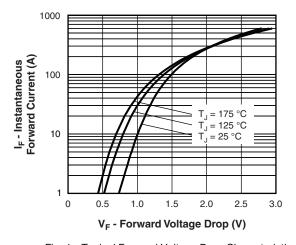


Fig. 1 - Typical Forward Voltage Drop Characteristics

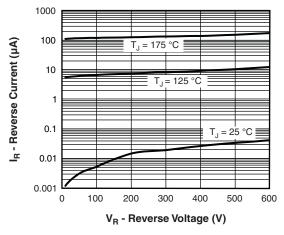


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

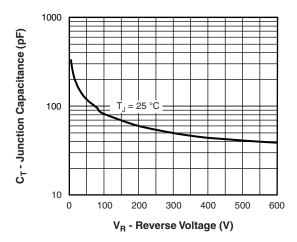


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

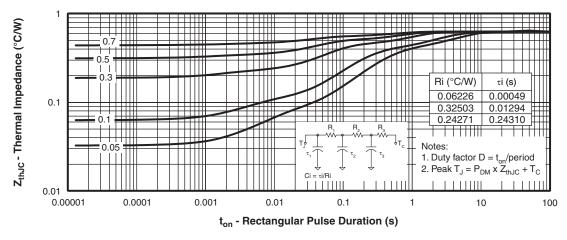


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

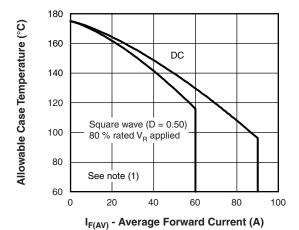
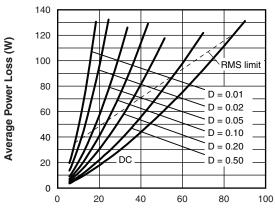


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current



I_{F(AV)} - Average Forward Current (A)

Fig. 6 - Forward Power Loss Characteristics

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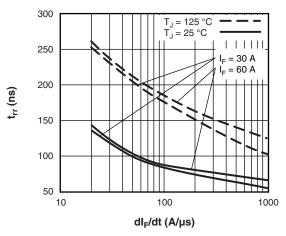


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

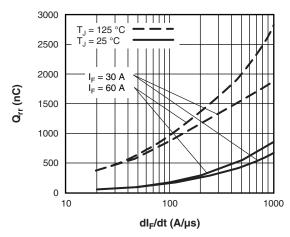


Fig. 8 - Typical Stored Charge vs. dl_F/dt

Note

 $^{(1)}$ Formula used: T_C = T_J - (Pd + Pd_{REV}) x R_{th,JC}; Pd = Forward power loss = I_{F(AV)} x V_{FM} at (I_{F(AV)}/D) (see fig. 6); Pd_{REV} = Inverse power loss = V_{R1} x I_R (1 - D); I_R at V_{R1} = 80 % rated V_R

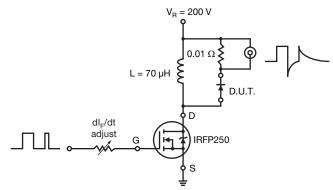
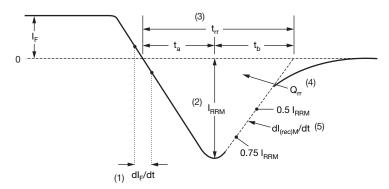


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) dl_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_{r}$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) \boldsymbol{Q}_{rr} area under curve defined by \boldsymbol{t}_{rr} and \boldsymbol{I}_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $dI_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

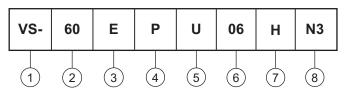
Fig. 10 - Reverse Recovery Waveform and Definitions

VS-60EPU06HN3, VS-60APU06HN3

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ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Current rating (60 = 60 A)

Circuit configuration:

• E = single diode

• A = single diode, 3 pins

P = TO-247AC (modified)

5 - U = ultrafast recovery

6 - Voltage rating (06 = 600 V)

7 - H = AEC-Q101 qualified

8 - Environmental digit:

N3 = halogen-free, RoHS-compliant and totally lead (Pb)-free

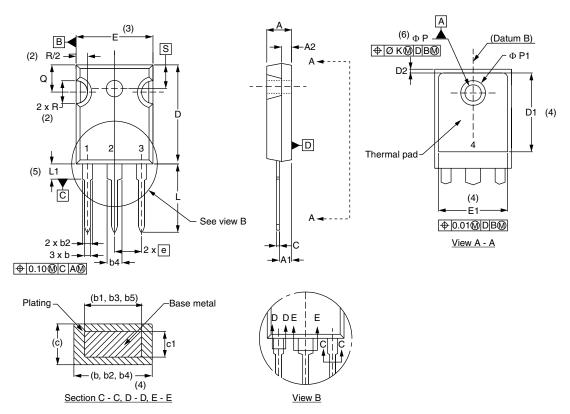
ORDERING INFORMATION (Example)						
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION			
VS-60EPU06HN3	25	500	Antistatic plastic tube			
VS-60APU06HN3	25	500	Antistatic plastic tube			

LINKS TO RELATED DOCUMENTS					
Dimensions	TO-247AC modified	www.vishay.com/doc?95253			
Differsions	TO-247AC	www.vishay.com/doc?95223			
Part marking information	TO-247AC modified	www.vishay.com/doc?95442			
Fart marking information	TO-247AC	www.vishay.com/doc?95007			
SPICE model		www.vishay.com/doc?95545			



TO-247AC

DIMENSIONS in millimeters and inches



SYMBOL	MILLIM	IETERS	INCHES		NOTES
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.65	5.31	0.183	0.209	
A1	2.21	2.59	0.087	0.102	
A2	1.50	2.49	0.059	0.098	
b	0.99	1.40	0.039	0.055	
b1	0.99	1.35	0.039	0.053	
b2	1.65	2.39	0.065	0.094	
b3	1.65	2.34	0.065	0.092	
b4	2.59	3.43	0.102	0.135	
b5	2.59	3.38	0.102	0.133	
С	0.38	0.89	0.015	0.035	
c1	0.38	0.84	0.015	0.033	
D	19.71	20.70	0.776	0.815	3
D1	13.08	-	0.515	-	4

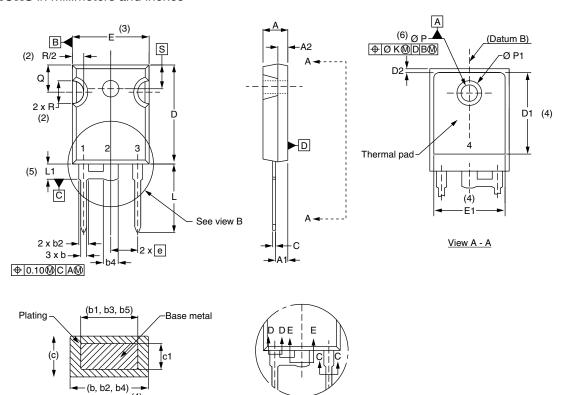
SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
D2	0.51	1.30	0.020	0.051	
E	15.29	15.87	0.602	0.625	3
E1	13.46	-	0.530	-	
е	5.46	BSC	0.215	BSC	
ØK	0.2	254	0.010		
L	14.20	16.10	0.559	0.634	
L1	3.71	4.29	0.146	0.169	
ØΡ	3.56	3.66	0.14	0.144	
Ø P1	ı	6.98	-	0.275	
Q	5.31	5.69	0.209	0.224	
R	4.52	5.49	0.178	0.216	
S	5.51	BSC	0.217 BSC		
	•		•	•	•

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- $^{(7)}$ Outline conforms to JEDEC® outline TO-247 with exception of dimension c

TO-247AC modified

DIMENSIONS in millimeters and inches



View B

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b4	2.59	3.43	0.102	0.135	
b5	2.59	3.38	0.102	0.133	
С	0.38	0.89	0.015	0.035	
c1	0.38	0.84	0.015	0.033	
D	19.71	20.70	0.776	0.815	3
D1	13.08	-	0.515	-	4

Section C - C, D - D, E - E

SYMBOL	MILLIN	IETERS	RS INCHES		NOTES
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
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